

# IRFR9110PBF-VB Datasheet P-Channel 100 V (D-S) MOSFET

| PRODUCT SUMMARY     |   |                    |                       |  |  |  |
|---------------------|---|--------------------|-----------------------|--|--|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}(\Omega)$                      | I <sub>D</sub> (A) | Q <sub>g</sub> (Typ.) |  |  |  |
| - 100               | $0.250 \text{ at V}_{GS} = -10 \text{ V}$ | - 8.8              | 11.7                  |  |  |  |
| - 100               | $0.280$ at $V_{GS} = -4.5 \text{ V}$      | - 8.0              | 11.7                  |  |  |  |

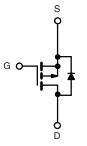
### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
  Compliant to RoHS Directive 2002/95/EC



### **APPLICATIONS**

- Power Switch
- DC/DC Converters



P-Channel MOSFET

| TO-252      |                        |
|-------------|------------------------|
| <del></del> |                        |
|             |                        |
|             |                        |
|             |                        |
|             |                        |
|             |                        |
|             | Drain Connected to Tab |
|             |                        |
| G D S       |                        |
| Top View    |                        |

| ABSOLUTE MAXIMUM RATINGS T <sub>C</sub> = 25 °C, unless otherwise noted |                                     |                                   |                   |      |  |
|---|-------------------------------------|-----------------------------------|-------------------|------|--|
| Parameter   |                                     |                                   | Limit             | Unit |  |
| Drain-Source Voltage  |                                     | V <sub>DS</sub>                   | - 100             |      |  |
| Gate-Source Voltage   | V <sub>GS</sub>                     | ± 20                              | V                 |      |  |
| Continuous Drain Current (T <sub>.I</sub> = 150 °C)                     | T <sub>C</sub> = 25 °C              | I-                                | - 8.8             |      |  |
| Continuous Diain Current (1) = 150 °C)                                  | T <sub>C</sub> = 70 °C              | - I <sub>D</sub>                  | - 7.1             |      |  |
| Pulsed Drain Current  |                                     | I <sub>DM</sub>                   | - 25              | Α    |  |
| Avalanche Current   |                                     | I <sub>AS</sub>                   | - 18              |      |  |
| Single Avalanche Energy <sup>a</sup>                                    | L = 0.1 mH                          | E <sub>AS</sub>                   | 16.2              | mJ   |  |
|   | T <sub>C</sub> = 25 °C              | Б                                 | 32.1 <sup>b</sup> | W    |  |
| Maximum Power Dissipation <sup>a</sup>                                  | T <sub>A</sub> = 25 °C <sup>c</sup> | - P <sub>D</sub>                  | 2.5               |      |  |
| Operating Junction and Storage Temperature R                            | ange                                | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 150       | °C   |  |

| THERMAL RESISTANCE RATINGS                   |                   |       |      |  |  |
|--|-------------------|-------|------|--|--|
| Parameter                                    | Symbol            | Limit | Unit |  |  |
| Junction-to-Ambient (PCB Mount) <sup>c</sup> | R <sub>thJA</sub> | 50    | °C/W |  |  |
| Junction-to-Case (Drain)                     | R <sub>thJC</sub> | 3.9   | C/VV |  |  |

### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

服务热线:400-655-8788

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| Parameter                                     | Symbol               | Test Conditions  | Min.  | Тур.  | Max.  | Unit    |  |
|---|----------------------|--|-------|-------|-------|---------|--|
| Static  |                      |  |       |       |       |         |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>      | $V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$                             | - 100 |       |       | V       |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$  | - 1   |       | - 2.5 | ٧       |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                            |       |       | ± 250 | nA      |  |
|   |                      | V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V                             |       |       | - 1   |         |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>     | V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C    |       |       | - 50  | - Fin 1 |  |
|   |                      | V <sub>DS</sub> = - 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C    |       |       | - 250 |         |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$                           | - 15  |       |       | Α       |  |
|   | Ь                    | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3.6 A                           |       | 0.250 |       | Ω       |  |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>  | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 3.4 A                          |       | 0.280 |       |         |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 3.6 A                           |       | 12    |       | S       |  |
| Dynamic <sup>b</sup>                          |                      |  |       | •     |       |         |  |
| Input Capacitance                             | C <sub>iss</sub>     |  |       | 1055  |       | pF      |  |
| Output Capacitance                            | C <sub>oss</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 50 V, f = 1 MHz                   |       | 65    |       |         |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     | 1  |       | 41    |       |         |  |
| Total Gate Charge <sup>c</sup>                |                      | V <sub>DS</sub> = - 50 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3.6 A |       | 23.2  | 34.8  |         |  |
|   | Qg                   |  |       | 11.7  | 17.6  |         |  |
| Gate-Source Charge <sup>c</sup>               | $Q_{gs}$             | $V_{DS} = -50 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3.6 \text{ A}$    |       | 3.5   |       |         |  |
| Gate-Drain Charge <sup>c</sup>                | $Q_{gd}$             |  |       | 4.8   |       |         |  |
| Gate Resistance                               | $R_g$                | f = 1 MHz  | 1.2   | 5.7   | 11.5  | Ω       |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |  |       | 7     | 14    |         |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD} = -50 \text{ V}, R_L = 17.2 \Omega$                                  |       | 12    | 18    |         |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  | $I_D \cong$ - 2.9 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$                  |       | 33    | 50    | ns      |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       | 1  |       | 9     | 18    |         |  |
| Drain-Source Body Diode Ratings ar            | nd Characteri        | stics T <sub>C</sub> = 25 °C <sup>b</sup>                                    |       |       |       |         |  |
| Continuous Current                            | I <sub>S</sub>       | Is   |       |       | - 8.8 |         |  |
| Pulsed Current                                | I <sub>SM</sub>      |  |       |       | - 15  | - 15 A  |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | I <sub>F</sub> = - 2.9 A, V <sub>GS</sub> = 0 V                              |       | - 0.8 | - 1.5 | V       |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      |  |       | 50    | 75    | ns      |  |
| Peak Reverse Recovery Current                 | I <sub>RM(REC)</sub> | I <sub>F</sub> = - 2.9 A, dl/dt = 100 A/μs                                   |       | - 4   | - 6   | Α       |  |
| Reverse Recovery Charge                       | Q <sub>rr</sub>      | † †  |       | 98    | 147   | nC      |  |

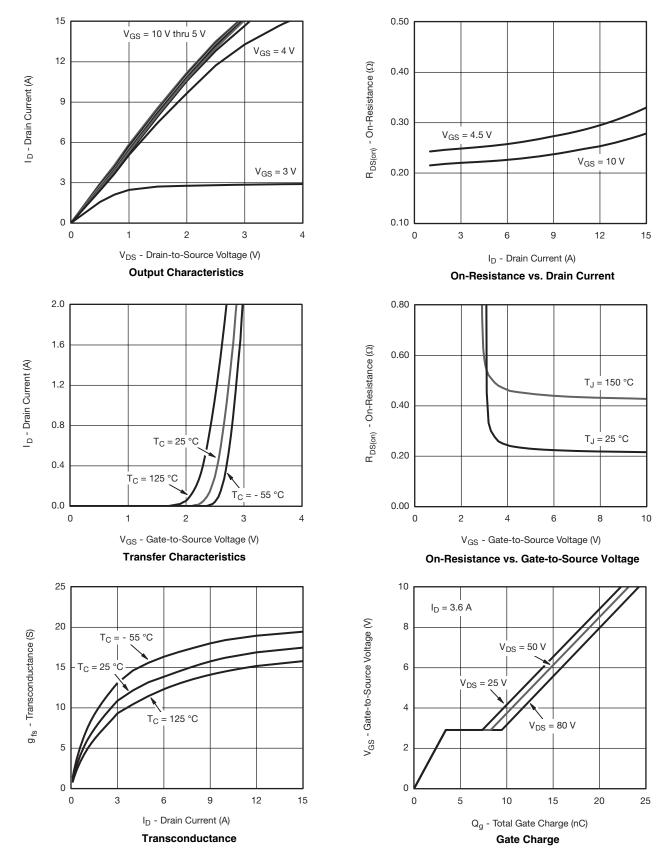
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

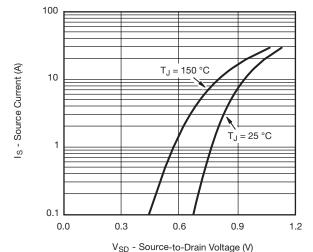


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

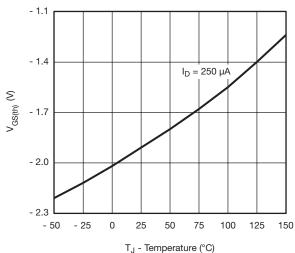




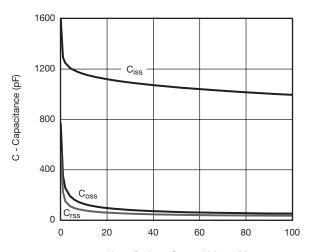
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



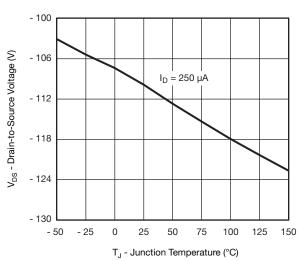
Source-Drain Diode Forward Voltage



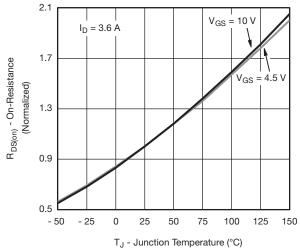
Threshold Voltage



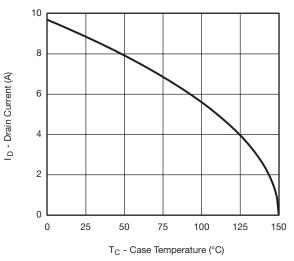
 $V_{DS}$  - Drain-to-Source Voltage (V)  $\label{eq:capacitance}$ 



**Drain Source Breakdown vs. Junction Temperature** 



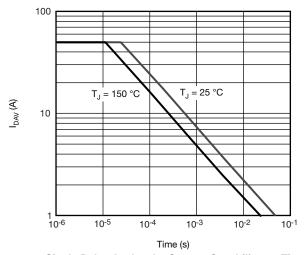
On-Resistance vs. Junction Temperature

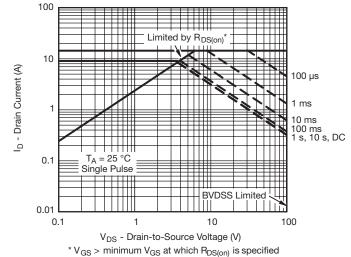


**Current Derating** 

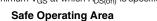


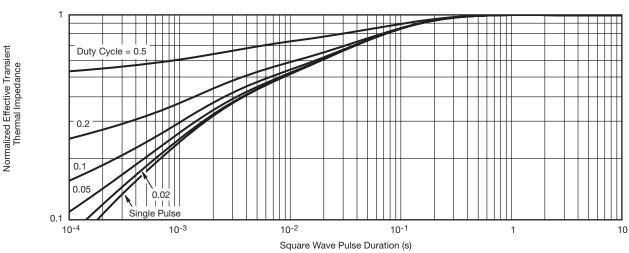
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Single Pulse Avalanche Current Capability vs. Time

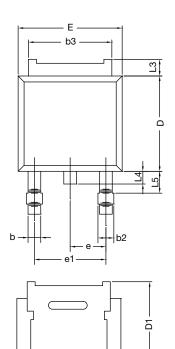


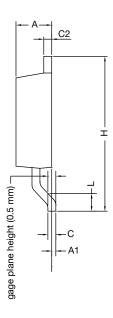


Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA Case Outline**





|                                 | MILLIMETERS |                 | INCHES    |       |
|---------------------------------|-------------|-----------------|-----------|-------|
| DIM.                            | MIN.        | MAX.            | MIN.      | MAX.  |
| А                               | 2.18        | 2.38            | 0.086     | 0.094 |
| A1                              | -           | 0.127           | -         | 0.005 |
| b                               | 0.64        | 0.88            | 0.025     | 0.035 |
| b2                              | 0.76        | 1.14            | 0.030     | 0.045 |
| b3                              | 4.95        | 5.46            | 0.195     | 0.215 |
| С                               | 0.46        | 0.61            | 0.018     | 0.024 |
| C2                              | 0.46        | 0.89            | 0.018     | 0.035 |
| D                               | 5.97        | 6.22            | 0.235     | 0.245 |
| D1                              | 4.10        | -               | 0.161     | -     |
| Е                               | 6.35        | 6.73            | 0.250     | 0.265 |
| E1                              | 4.32        | -               | 0.170     | -     |
| Н                               | 9.40        | 10.41           | 0.370     | 0.410 |
| е                               | 2.28        | 3 BSC 0.090 BSC |           | BSC   |
| e1                              | 4.56        | BSC             | 0.180 BSC |       |
| L                               | 1.40        | 1.78            | 0.055     | 0.070 |
| L3                              | 0.89        | 1.27            | 0.035     | 0.050 |
| L4                              | -           | 1.02            | -         | 0.040 |
| L5                              | 1.01        | 1.52            | 0.040     | 0.060 |
| ECN: T16-0236-Rev. P, 16-May-16 |             |                 |           |       |

DWG: 5347

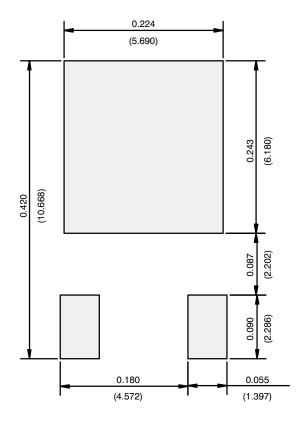
#### Notes

• Dimension L3 is for reference only.



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### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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